



Click [here](#) for the 3D model.

Dimensions	
D	25.715mm +/-1.585mm
L	1.78mm +/-0.25mm
T	1.397mm MAX
S	2.54mm TYP
F	0.254mm +/-0.051mm
A	16.51mm MAX
C	11.43mm +/-0.635mm
E	12.7mm MAX
LO	1.586mm MAX
LW	0.508mm +/-0.051mm
MP	1.27mm MIN

Packaging Specifications	
Packaging	Waffle, Box
Packaging Quantity	28

General Information	
Series	KPS LDD Comm SMPS
Style	Leaded Stacked Chip
Description	Low ESR, High Current Stacked Ceramic Chips
Features	Low ESR, High Current, High Performance
RoHS	No
Prop 65	<b>⚠ WARNING:</b> Cancer and reproductive harm - <a href="http://www.p65warnings.ca.gov">http://www.p65warnings.ca.gov</a> .
Termination	60/40 Solder Coated
Lead	J Leads
Failure Rate	N/A
Testing and Reliability	Commercial
AEC-Q200	No
Notes	Note: Number of chips in stack depends on design. Number of Chips in this stack = 5. Note: Turn Radius For Lead Extension Is 0.1 Radians (Typical). Note: Lead alignment within pin rows shall be within ±0.13 mm.

Specifications	
Capacitance	12 uF
Capacitance Tolerance	10%
Voltage DC	500 VDC
Dielectric Withstanding Voltage	750 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Dissipation Factor	2.5% 120 Hz 25C
Aging Rate	3% Loss/Decade Hour
Insulation Resistance	8.3 GOhms

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